*М*ЛХГМ EVALUATION KIT **Dual 300mA Pin-Programmable LDO Linear Regulators**

© Pin-Programmable Output Voltages

© Low 90mV Dropout at 100mA Load

© Low 54µA Quiescent Supply Current

© Low < 1µA Maximum Shutdown Current</p>

© Open-Drain, Active-Low RESET (MAX8633)

© Low 45µV_{RMS} Output Noise (MAX8634/MAX8636)

© Thermal Shutdown _____Ordering Information

PIN-PACKAGE

8 µDFN

8 TDFN

8 µDFN

2mm x 2mm

3mm x 3mm

2mm x 2mm

Note: All are devices specified over the extended -40°C to

© 300mA Output Current

© Output Current Limit

PART

MAX8633ELA+

MAX8633ETA+

MAX8634ELA+

General Description

The MAX8633-MAX8636 offer low-dropout (LDO) voltage and ultra-low-power regulation in a subminiaturized 2mm x 2mm µDFN package. The devices operate from a 2.7V to 5.5V supply and deliver up to 300mA from each output, with a typical dropout voltage of 90mV at 100mA load current. Each device is designed with internal p-channel MOSFET pass transistors to ensure a low-quiescent supply current of 54µA (typical, both LDOs on). Other features include low-noise operation (MAX8634/MAX8636), output current limiting, and thermal shutdown.

19-0516; Rev 0; 4/06

AVAILABLE

The MAX8633 features an open-drain, active-low RESET output to monitor OUT2, eliminating external components and adjustments. The MAX8633 asserts a RESET signal (120ms minimum timeout) when VOUT2 drops below 87% of the nominal output voltage. The MAX8634/MAX8636 feature a noise bypass input to the internal reference for low output noise (45µVRMS typ). The MAX8634/MAX8635 provide independent SHDN inputs for disabling the regulators, while the MAX8633/ MAX8636 provide a single SHDN input for disabling both regulators.

The MAX8633/MAX8635/MAX8636 have two logic inputs that select one of nine preset output-voltage combinations, eliminating external 1% resistors, as well as inventory burden. The MAX8634 has one logic input to select three output-voltage options.

The MAX8633–MAX8636 are available in an 8-pin. 2mm x 2mm µDFN package for minimizing footprint, and an 8-pin, 3mm x 3mm TDFN package for higher power dissipation. The devices are specified over the extended temperature range (-40°C to +85°C). All packages are lead free.

Applications

Cellular and Cordless Phones PDAs and Digital Cameras Small LCD Displays Notebook Computers Wireless LAN Cards Handheld Instruments

Pin Configurations and Selector Guide appear at end of data sheet.

M/X/M

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+Indicates lead-free package. Ordering Information continued at end of data sheet.

+85°C operating temperature range.

Typical Operating Circuits

TOP

MARK

AAH

AOQ

AAI



Features

PKG

CODE

L822-1

T833-2

L822-1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

(All voltages refer to GND, unless otherwise noted.)

SHDN, SHDN1, SHDN2, RESET, P. P1, P2, RP, OUT, COMPARENT, COMPAREN

P, P1, P2, BP, OUT1, OUT2.....-0.3V to (VIN + 0.3V) Continuous Output Short-Circuit Duration......Continuous Continuous Power Dissipation ($T_A = +70^{\circ}C$) 8-Pin µDFN 2mm x 2mm

8-Pin TDFN 3mm x 3mm	
(derate 23.8mW/°C above +70°C)	1904mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VIN = 3.7V, SHDN = SHDN1 = SHDN2 = IN, P = P1 = P2 = GND, CIN = 2.2µF, COUT1 = 2.2µF, COUT2 = 2.2µF, CBP = 0.01µF, TA = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	МАХ	UNITS
Input Voltage	VIN			2.7		5.5	V
Input Undervoltage Lockout	Vuvlo	V _{IN} rising; hysteresis =	V _{IN} rising; hysteresis = 95mV (typ)		2.25	2.35	V
		I _{OUT} = 0mA	I _{OUT} = 0mA			75	
Ground Current	IQ	$I_{OUT} = 100 \text{mA}$			60		μA
		I _{OUT} = 10mA, dropout	(Note 2)		60		
Shutdown Supply	loss	SHDN_ = GND	$T_A = +25^{\circ}C$		0.005	1	μA
Current	IOFF		$T_A = +85^{\circ}C$		0.01		μΑ
OUT1, OUT2							
		$I_{OUT} = 70 \text{mA}; T_{A} = +25^{\circ}\text{C}$		-0.7		+0.7	- %
Output Voltage Accuracy (for Any		I _{OUT} = 70mA	-1		+1		
Output Voltage)		I_{OUT} = 0.1mA to 300mA; V_{IN} = (V_{OUT} + 0.5V) to 5.5V		-1.8		+1.7	
Current Limit	I _{LIM}	OUT_ = 0V		400	500	600	mA
Drop-Out Voltage	V _{IN} - V _{OUT}	$V_{OUT} = 2.85V$ (MAX86	V _{OUT} = 2.8V (MAX8633); V _{OUT} = 2.85V (MAX8634/MAX8635/MAX8636); I _{OUT} = 100mA (Note 2)			200	mV
Output Noise		f = 10Hz to 100kHz;	MAX8633 MAX8635		450		
		I _{OUT} = 10mA	MAX8634 MAX8636		45		– μVRMS
Output AC Power-	DODD	lour - 20mA	f < 1kHz		60		dP
Supply Rejection PSRR Ratio		I _{OUT} = 30mA	f < 10kHz	55			dB

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 3.7V, \overline{SHDN} = \overline{SHDN1} = \overline{SHDN2} = IN, P = P1 = P2 = GND, C_{IN} = 2.2\mu$ F, $C_{OUT1} = 2.2\mu$ F, $C_{OUT2} = 2.2\mu$ F, $C_{BP} = 0.01\mu$ F, $T_A = -40^{\circ}$ C to +85°C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}$ C.) (Note 1)

PARAMETER	SYMBOL	COI	CONDITIONS			MAX	UNITS
SHUTDOWN INPUTS	SHDN, SHDN	1, AND SHDN2)					
Input Voltage High	VIH	$V_{IN} = 2.7V$ to 5.5V	V _{IN} = 2.7V to 5.5V				V
Input Voltage Low	VIL	$V_{IN} = 2.7V \text{ to } 5.5V$	/ _{IN} = 2.7V to 5.5V			0.5	V
Input Bias Current		$V_{IN} = 2.7V$ to 5.5V;	$T_A = +25^{\circ}C$		0.1	1000	nA
Input bias Current	ISHDN_	V_{SHDN} = GND or IN	$T_A = +85^{\circ}C$		1		ΠA
Turn-On Delay		From \overline{SHDN} = high to 87 I _{OUT} = 70mA	From $\overline{\text{SHDN}}$ = high to 87% of V _{OUT_} ; I _{OUT} = 70mA		90		μs
TRI-LEVEL INPUTS (P	, P1, P2)						-
Termination Resistance to IN or		IN = 2.7 to 5.5V	For high or low state			1	- kΩ
GND for Setting High, Open, and Low States		110 = 2.7 10 5.5 V	For open state	100			KΩ
Input Load Capacitance for Open State		Design guide only				50	pF
RESET		·					
RESET High Threshold		Percent of nominal OUT	Percent of nominal OUT2; OUT2 rising		87	90	%
RESET Threshold Hysteresis		Percent of nominal OUT	2; OUT2 falling		4.5		%
RESET Output		$I_{\overline{RESET}} = 20\mu A; V_{IN} = 1.0$	V		10	100	mV
Voltage Low		$I_{RESET} = 500 \mu A; V_{IN} = 3$			5	100	IIIV
RESET Output High Leakage Current	ILEAK	$V_{\overline{\text{RESET}}} = V_{IN} = 5.5V$	$T_{A} = +25^{\circ}C$ $T_{A} = +85^{\circ}C$		0.1	300	nA
RESET Delay	t _{RP}	From OUT2 rising to RESET rising		120	150	180	ms
THERMAL PROTECTI	ON	·					
Thermal-Shutdown Threshold	T _{SHDN}				+165		°C
Thermal-Shutdown Hysteresis	ΔT_{SHDN}				15		°C

Note 1: All units are 100% tested at $T_A = +25^{\circ}$ C. Limits over the operating temperature range are guaranteed by design.

Note 2: The dropout voltage is defined as $V_{IN} - V_{OUT}$ when V_{OUT} drops by 100mV from V_{OUT} when measured at $V_{IN} = +3.7V$. **Note 3:** Connect P_ to IN or GND through a resistor less than 1k Ω .



Typical Operating Characteristics

MAXIM

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Typical Operating Characteristics (continued)

(VIN = 3.8V, P = P1 = P2 = GND, I_{OUT1, 2} = 70mA, C_{OUT1} = 2.2µF, C_{OUT2} = 2.2µF, C_{BP} = 0.01µF, C_{IN} = 2.2µF, and T_A = +25°C, unless otherwise noted.)



Pin Description

	P	IN			
MAX8633	MAX8634	MAX8635	MAX8636	NAME	FUNCTION
1	1	1	1	IN	Regulator Input. Supply voltage from 2.7V to 5.5V. Bypass IN with a ceramic capacitor of at least 2.2µF to GND (see the <i>Capacitor Selection and Regulator</i> <i>Stability</i> section).
2	_	_	2	SHDN	Shutdown Input, Active Low. Drive SHDN logic low to shut down both regulators. Connect SHDN to IN or drive logic high for normal operation (see the <i>Power-On Sequence (MAX8633/Max8636 Only)</i> section).
_	2	2	_	SHDN1	LDO1 Shutdown Input, Active Low. Drive SHDN1 logic low to shut down OUT1. Connect SHDN1 to IN or drive logic high for normal operation.
—	3	5	_	SHDN2	LDO2 Shutdown Input, Active Low. Drive SHDN2 logic low to shut down OUT2. Connect SHDN2 to IN or drive logic high for normal operation.
3	—	3	3	P2	Programming Input 2. The state of P1 and P2 selects one of nine output-voltage options (see Tables 1, 3).
4	_	4	4	P1	Programming Input 1. The state of P1 and P2 selects one of nine output-voltage options (see Tables 1, 3).
_	4		_	Р	Programming Input. The state of P selects one of three output-voltage options for the MAX8634 (see Table 2).
5				RESET	Reset Output, Active Low, Open Drain. RESET goes high impedance 120ms (min) after V_{OUT2} rises above 87% of the nominal output voltage. RESET is forced logic low when V_{OUT2} is below 82.5% of the nominal output voltage. Connect RESET to OUT1, OUT2, or another voltage of V_{IN} or lower with a pullup resistor.
—	5	_	5	BP	Reference Noise Bypass. Bypass BP to GND with a 0.01µF ceramic capacitor to reduce output noise.
6	6	6	6	GND	Ground
7	7	7	7	OUT2	Regulator 2 Output. Guaranteed 300mA output current (see the <i>Calculating Maximum Output Power</i> section). Bypass OUT2 with a ceramic capacitor of at least 2.2µF to GND (see the <i>Capacitor Selection and Regulator</i> <i>Stability</i> section).
8	8	8	8	OUT1	Regulator 1 Output. Guaranteed 300mA output current (see the <i>Calculating Maximum Output Power</i> section). Bypass OUT1 with a ceramic capacitor of at least 2.2µF to GND (see the <i>Capacitor Selection and Regulator</i> <i>Stability</i> section).
EP*	EP*	EP*	EP*	EP	Exposed Paddle. Solder the exposed paddle to a large pad or circuit-board ground plane to increase thermal dissipation.

*TDFN package only.

MAX8633-MAX8636

Functional Diagram



Detailed Description

The MAX8633–MAX8636 are low-power, low-quiescent current, low-dropout linear regulators designed primarily for battery-powered applications. Pin-programmable inputs allow easy configuration of OUT1 and OUT2 voltages without external 1% resistors. The devices can supply up to 300mA from each output, provided they do not exceed the maximum package power dissipation.

The MAX8633–MAX8636 regulate OUT1 and OUT2 by using simple control loops incorporating internal 1.50V reference, error amplifiers, p-channel pass transistors, and internal feedback voltage-dividers. Reset circuitry ensures controlled startup and provides undervoltage lockout. The MAX8633–MAX8636 determine output voltages at OUT1 and OUT2 based on the state of P1 and P2 (P for MAX8634) at power-on.

RESET (MAX8633)

The MAX8633 features an integrated reset circuit. RESET is logic-low on power-up and goes high impedance 150ms after OUT2 reaches 87% of its nominal regulation voltage. During power-down or undervoltage conditions, RESET is driven low when OUT2 falls below 82.5% of its nominal regulation voltage.

Output Programming Inputs (P1, P2, P)

Output voltages for OUT1 and OUT2 are determined at power-up by the state of P1 and P2. Programming inputs P1 and P2 eliminate external 1% feedback resistors while providing nine preset output-voltage options (see Table 1 for the MAX8633; see Table 3 for the MAX8635/MAX8636).

The MAX8634 provides three preset output-voltage options with one programming input (see Table 2). The MAX8633–MAX8636 configure output voltages at OUT1 and OUT2 based on the state of P1 and P2 (P for

Table 1. Output-Voltage Programming(MAX8633)

P1	P2	OUT1 (V)	(OUT2) (V)
Open	Open	2.80	1.50
Open	GND	2.90	1.50
Open	IN	3.00	1.50
GND	Open	3.00	1.60
GND	GND	2.80	1.80
GND	IN	2.60	1.85
IN	Open	2.90	1.85
IN	GND	2.80	2.60
IN	IN	3.00	2.80

MAX8634) at power-on. Subsequent changes to P, or P1 and P2 do not change the output voltages unless the supply power is cycled, or all SHDN inputs are simultaneously driven low to shut down the device.

Power-On Sequence (MAX8633/MAX8636 Only)

The MAX8633/MAX8636 provide a single shutdown input (SHDN) to disable OUT1 and OUT2. During power-on, inrush current is limited by a built-in startup sequence. At power-on, OUT1 is disabled until OUT2 reaches 87% of its regulation voltage, then OUT1 is enabled.

Internal p-Channel Pass Transistor

The MAX8633–MAX8636 feature 0.9Ω p-channel MOSFET pass transistors; p-channel MOSFETs provide several advantages over similar designs using pnp pass transistors, resulting in higher efficiency and longer battery life. MOSFET pass transistors do not require base drive current of pnps, reducing quiescent current considerably. Under heavy loads, pnp base-drive current becomes large, further reducing efficiency; pnp-based regulators also require considerable current in dropout when the pass transistor saturates. The MAX8633–MAX8636 do not suffer from these problems. With both outputs active, the devices consume only 54µA of quiescent current at no load, and 60µA with 100mA load

Table 2. Output-Voltage Programming(MAX8634)

Р	OUT1 (V)	OUT2 (V)
Open	2.85	2.85
GND	3.00	2.85
IN	2.60	2.60

Table 3. Output-Voltage Programming(MAX8635/MAX8636)

P1	P2	OUT1 (V)	OUT2 (V)
Open	Open	2.80	1.50
Open	GND	2.90	1.50
Open	IN	3.00	1.50
GND	Open	2.60	1.80
GND	GND	2.80	1.80
GND	IN	3.00	2.50
IN	Open	3.00	2.80
IN	GND	2.85	2.85
IN	IN	3.00	3.00



current for each output (see *Typical Operating Characteristics*). A pnp-based regulator has a high dropout voltage that is independent of the load. The dropout voltage of a p-channel MOSFET is proportional to load current providing for low-dropout voltage at heavy loads and extremely low dropout at lighter loads.

Current Limit

The MAX8633–MAX8636 provide independent current limiting for OUT1 and OUT2. Output current is limited to 500mA (typ) and 400mA (min) for each regulator.

Shutdown (SHDN1, SHDN2, SHDN)

The MAX8634/MAX8635 have independent shutdown control inputs (SHDN1 and SHDN2) and the MAX8633/MAX8636 have one shutdown control input (SHDN) for both outputs. Drive SHDN1 low to shut down OUT1. Drive SHND2 low to shut down OUT2. Drive both SHDN1 and SHDN2 low to shut down the entire device, reducing supply current to 1 μ A max. For the MAX8634, drive SHDN1 low to shut down the entire device. Connect SHDN1, SHDN2, or SHDN to a logic-high or IN to permanently enable the corresponding LDO(s).

Thermal-Overload Protection

Thermal-shutdown circuitry protects the MAX8633–MAX8636 from damage due to excessive junction temperature. The shutdown circuit disables OUT1 and OUT2 when the junction temperature (T_J) exceeds +165°C. Both regulators are reenabled when T_J falls by 15°C.

Low-Noise Operation (MAX8634/MAX8636)

An external 0.01µF bypass capacitor at BP in conjunction with an internal resistor creates a lowpass filter. The MAX8634/MAX8636 exhibit less than 45μ V_{RMS} of output voltage noise with C_{BP} = 0.01µF and C_{OUT} = 2.2µF. These values are shown in the Output Noise Spectral Density graph in the *Typical Operating Characteristics* section. If output noise is not critical, omit the BP capacitor to reduce total solution size and cost.

Applications Information

Capacitor Selection and Regulator Stability

Use a ceramic input capacitor of at least 2.2µF and a ceramic output capacitor of at least 2.2µF for each output to ensure stable operation over the entire temperature range. Output capacitors can be reduced to 1µF for load currents less than 150mA. The MAX8633–MAX8636 are optimized for ceramic capacitors and require low equivalent-series resistance (ESR) to achieve the stated specifications for low-output noise and power-supply rejection. To ensure proper operation over the specified temperature range, dielectrics



such as X7R or X5R are recommended. If Z5U or Y5V dielectrics are used, it may be necessary to increase the value of the output capacitors to ensure stability at temperatures below -10°C. Tantalum capacitors are not recommended due to their higher ESR.

For loads up to 300mA, or for improved load-transient response, 2.2μ F or larger output capacitors can be used.

PSRR and Operation from Sources Other than Batteries

The MAX8633–MAX8636 deliver low-dropout voltages and low-quiescent currents in battery-powered systems. When operating from sources other than batteries, improved supply-noise rejection and transient response can be achieved by increasing the values of the input and output capacitors and through passive filtering techniques. Power-supply rejection is 60dB at frequencies below 1kHz (see the Power-Supply Rejection Ratio vs. Frequency in the *Typical Operating Characteristics*).

P1 and P2 (P for MAX8634) External Termination

The pin-programmable inputs (P1 and P2 for MAX8633/MAX8635/MAX8636, P for MAX8634) should be connected to IN, GND, or left open. If P_ inputs are left open, ensure the external capacitance is less than 50pF. If P_ inputs are set high or low, ensure the resistance to IN or GND is less than 1k Ω . The MAX8633–MAX8636 configure output voltages at OUT1 and OUT2 based on the state of P1 and P2 (P for MAX8634) at power-on. Subsequent changes to P, or P1 and P2 do not change the output voltages unless the supply power is cycled, or all SHDN inputs are simultaneously driven low to shut down the device.

Load-Transient Considerations

The MAX8633–MAX8636 load-transient response graphs (see *Typical Operating Characteristics*) show two components of the output response: a DC step in the output voltage due to the change in load current, and the transient response. Increase the value and decrease the ESR of the output capacitor to attenuate transient spikes.

Input-Output Voltage (Dropout Voltage)

A regulator's minimum input-output voltage differential (or dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the MAX8633–MAX8636 use a p-channel MOSFET pass transistor, dropout voltage is a function of drainto-source on-resistance (R_{DS(ON)}) multiplied by the load current (see *Typical Operating Characteristics*).

Calculating Maximum Output Power

The maximum output power of the MAX8633–MAX8636 is limited by the maximum power dissipation of the package. By calculating the power dissipation of the device as a function of the input voltage, output voltages, and output currents, the worst-case power dissipation can be obtained. The worst-case power dissipation should not exceed the package's maximum power rating:

where:

$$P_{D} = (V_{IN(MAX)} - V_{OUT1}) \times I_{OUT1} + (V_{IN(MAX)} - V_{OUT2}) \times I_{OUT2}$$

VIN(MAX) = Maximum input voltage

VOUT1 = Output voltage of OUT1

VOUT2 = Output voltage of OUT2

IOUT1 = Maximum output current of OUT1

IOUT2 = Maximum output current of OUT2

 P_D must be less than $P_{DMAX},$ the maximum power dissipation of the package. If P_D is greater than $P_{DMAX},$ consider using the 8-pin TDFN package.

 $P_{DMAX} = 380 \text{mW}$ for the 8-pin µDFN. Derate by $4.8 \text{mW/}^{\circ}\text{C}$ above +70°C.

 P_{DMAX} = 1904mW for the 8-pin TDFN. Derate by 23.8mW/°C above +70°C.

PC Board Layout Guidelines

Follow these guidelines for good PC board layout:

- Keep the input and output traces short and wide if possible, especially at the ground terminals.
- Use thick copper PC boards to enhance thermal performance. Connect the exposed paddle of the TDFN package to the ground plane or a large copper pad.
- Place output, input, and bypass capacitors as close as possible to the IC.
- Ensure the noise bypass capacitor and associated PC board traces are routed away from noise sources to ensure low-output voltage noise.

An evaluation kit (MAX8633EVKIT) is available for a layout example to speed designs.

PART	OUTPUT VOLTAGE OPTIONS	SHDN INPUTS	LOW NOISE	RESET
MAX8633	9	1	_	YES
MAX8634	3	2	YES	—
MAX8635	9	2		_
MAX8636	9	1	YES	—

Selector Guide

Ordering Information (continued)

PART	PIN-PACKAGE	TOP MARK	PKG CODE
MAX8634ETA+	8 TDFN 3mm x 3mm	AOR	T833-2
MAX8635ELA+	8 µDFN 2mm x 2mm	AAJ	L822-1
MAX8635ETA+	8 TDFN 3mm x 3mm	AOS	T833-2
MAX8636ELA+	8 µDFN 2mm x 2mm	AAK	L822-1
MAX8636ETA+	8 TDFN 3mm x 3mm	AOT	T833-2

Note: All are devices specified over the extended -40°C to +85°C operating temperature range.

/N/IXI/N

_Pin Configurations



_Chip Information

PROCESS: BICMOS CONNECT EXPOSED PADDLE TO GND.

_Typical Operating Circuits



Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to **www.maxim-ic.com/packages**.)



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